

ICP-RIE (Oxford Plasmalab 100) Basic User Manual



3rd Edition September 2012, NR



1) ICP-RIE System Overview



ICP-RIE Loadlock









Logon RIE Oxford Plasmalab on FOM System

Sign Log Book



"L - FOM - S	chedule				
	Notes from instrument manager		and an and the later to the		
	Contact valual retries 2 rotors in advance for the Start Op and availability. Instrument Schedule: RIE Oxford Plasmalab - RIE Oxford Plasmalab is now /vallable - Your user level on this instrument is instrument Manager.				
me on server					
onday Apr. 8					
15:04:41	02/11 02/18 02/25 03/04 03/11	03/18 03/25 04/01		Today Apr 8, 20	13
n Home	Mon 04/08	Tue 04/09	Wed 04/10	[Thu 04/11	Fri 04/12
Home	** ** ** **	he ee ee ee		Click to show sessions from n	midnight to 09:00
wford Plasn	09:00 - 09:30	09:00 - 09:30	09:00 - 09:30	09:00 - 09:30	09:00 - 09:3
	09:30 - 10:00	09:30 - 10:00	09:30 - 10:00	09:30 - 10:00	09:30 - 10:0
Abit riem manur 💌	10:00 - 10:30	Instrumer	t Logon		10:00 - 10:3
rtments	10:30 - 11:00	10 mouther	it Logon		10:30 - 11:0
visors	11:00 - 11:30				11:00 - 11:3
urces Admin	11.30 - 12.00	Previous user comment:			11:30 - 12:0
anance Records	12:00 - 12:30	Service We	Service Work in PO 031513-01		
	12.30 - 13.00	Consumables	6		12:30 - 13:0
Admin	13:00 - 13:30	13			13:00 - 13:3
List	13.30 - 14.00	Confirm instru	ment logon:		13.30 - 14.0
oorate & Service	14.00 - 14.50	14 14 Yes Cancel this session			14:00 - 14:0
e Records	14:30 - 15:00				14:30 - 15:0
	Click to log on	10			15.00 - 15.3
ase Supplies	Nathan Reed, 15:30-16:00	15			15:30 - 16:0
ments	16:00 - 16:30	10			10:00 - 10:3
Report	16:30 - 17:00	10			10.30 - 17.0
ofile	17:00 - 17:30	17			17.00 - 17.3
counte	17:30 - 18:00	1/	40.00 40.00	40.00 40.00	17:30 - 18:0
et Managar	18:00 - 18:30	18.00 - 18.30	18.00 - 18.30	18.00 - 18.30	18.00 - 18.3
ict manager	18:30 - 19:00	18.30 - 19.00	18.30 - 19.00	18.30 - 19.00	10.30 - 19.0
ut	19:00 - 19:30	19:00 - 19:30	19:00 - 19:30	19:00 - 19:30	19:00 - 19:3
Forum	19:30 - 20:00	19.30 - 20.00	19.30 - 20.00	19.30 - 20.00	19.30 - 20.0
	20:00 - 20:30	20:00 - 20:30	20:00 - 20:30	20:00 - 20:30	20:00 - 20:3
	20:30 - 21:00	20.30 - 21.00	20:30 - 21:00	20.30 - 21.00	20.30 - 21.0
	21:00 - 21:30	21.00 - 21.30	21.00 - 21.30	21.00-21.30	21.00 - 21.3
	21:30 - 22:00	21:30 - 22:00	21:30 - 22:00	21:30 - 22:00	21:30 - 22:0
	22.00 - 22:30	22:00 - 22:30	22:00 - 22:30	22:00 - 22:30	22:00 - 22:3
	22.30 - 23:00	22.30 - 23.00	22.30 - 23.00	22.30 - 23.00	22.30 - 23:0
	23:00 - 23:30	23:00 - 23:30	23:00 - 23:30	23:00 - 23:30	23:00 - 23:3
	23.30 - 00.00	23.30 - 00:00	23.30 - 00.00	23.30 - 00.00	23:30 - 00:0





2) Vent Loadlock

- Under "Cycling Loadlock Pumping" click **Stop** then **Vent**
- Wait until "Vent Time Left" is 0 secs (150 sec total vent time)
- Open the Loadlock chamber door









Washington University in St. Louis School of Engineering & Applied Science

> Nanoscale Science, Engineering & Technologi,

3) Insert Wafer

- Add wafer to Loadlock with the flat edge between the pins and close lid
- Click Stop → Evacuate in the Loadlock panel
- Enter a Wafer Name in the "Load Wafer or pump loadlock" pop-up window → click OK





Washington University in St. Louis School of Engineering & Applied Science

4) Recipe

- Input your recipe temperature in the temperature control box
- Push the T button → use the arrow keys to select a "Temperature Setpoint" → input a new temperature using the number keypad if needed → push OK
- In the PC2000 software go to "Process \rightarrow Recipes"





Nanoscale Science, Engineering & Technologi

NANO RESEARCH FACILITY

SCHOOL OF ENGINEERING & APPLIED SCIENCE

Recipe cont.

- Click Load and choose a recipe from the list
- When the temperature control box reaches the desired temperature start the etch process by clicking **Run**

(recipes should include a pump step before (PTP) and after the etching step (PTB) to automatically pump down the Loadlock, move the wafer into the process chamber, pump down the process chamber after etching, and move the wafer back to the Loadlock)







NANO RESEARCH FACILITY

Washington University in St.Louis

SCHOOL OF ENGINEERING & APPLIED SCIENCE

Recipe cont.

• You may edit a recipe that has been loaded by clicking on a step in the list on the left and choosing "Edit Step"

• Make a new recipe by clicking **New** → in pop-up window "Clear current recipe?" click **OK** → then click in the recipe step box on the left and choose "Insert Step" or click and drag a preprogrammed step from the "Step Library" list on the right into the recipe box and choose "Edit Step"





Recipe cont.

 In the "Process Step Editor" input Step Name, Step Time, Process Gas flows, Chamber Pressure, Helium Backing Pressure, RF Generator Forward Power, and ICP Generator Forward Power

- Click **OK** when done or if button is grayed out press **Enter** on the keyboard (press Esc to cancel)
- In the "Recipe" screen give the recipe a new name and click **Save**





Nanoscale Science, Engineering & Technology

NANO RESEARCH FACILITY

Washington University in St.Louis

SCHOOL OF ENGINEERING & APPLIED SCIENCE

5) Etch Process

- During the etch process the chamber screen will display the recipe progress and all input gas, power, and pressure settings
- When the etch process is complete a "Yellow Alert" window will pop up to notify you of the process completion → click
 Continue
- (It is normal for this alert to remain active in the right hand corner of the screen)





Washington University in St.Louis

SCHOOL OF ENGINEERING & APPLIED SCIENCE

Etch Process cont.

- In the pop-up window "Wafer has finished processing. Ready to be removed." click **OK**
- Click Stop → Vent in the Loadlock panel and wait for the vent cycle to finish
- Remove your wafer and insert another → repeat steps starting on page 11







6) Shut down

 When done using the instrument remove your sample, close the Loadlock door, and click Stop → Evacuate in the Loadlock panel



